

Type number	Package	Package description	Total product weight
74AUP1G58GM	SOT886	XSON6	1.90508 mg

12NC	Version	Pb-free soldering			Pb soldering			Number of processing cycles	Assembly site	RHF-indicator
		MSL	PPT	MPPT	MSL	PPT	MPPT			
935279961132	7	1	260	30 s	1	240	20 s	3	Nijmegen, Netherlands; Bangkok, Thailand; Seremban, Malaysia	
935279961115	8	1	260	30 s	1	240	20 s	3	Seremban, Malaysia; Bangkok, Thailand; Nijmegen, Netherlands	

Subpart	Material group	Substances	CAS number	Mass(mg)	Mass(%) of subpart	Mass(%) of total product
Die	Doped silicon	Silicon (Si)	7440-21-3	0.04510	100.00000	2.36751
		subTotal		0.04510	100.00000	2.36751
Component	Additive	Non hazardous	Proprietary	0.00025	5.00000	0.01312
	Filler	Bisphenol-A/Epichlorohydrin Epoxy resin (generic)	25068-38-6	0.00025	5.00000	0.01312
		Silica -amorphous-	7631-86-9	0.00250	50.00000	0.13123
	Polymer	Epoxy resin system	Proprietary	0.00150	30.00000	0.07874
		Phenol Formaldehyde resin (generic)	9003-35-4	0.00050	10.00000	0.02625
		subTotal		0.00500	100.00000	0.26246
Lead Frame	Copper alloy	Copper (Cu)	7440-50-8	0.73232	94.86000	38.44034
		Magnesium (Mg)	7439-95-4	0.00116	0.15000	0.06078
		Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.02285	2.96000	1.19949
		Silicon (Si)	7440-21-3	0.00494	0.64000	0.25935
	Pure metal layer	Gold (Au)	7440-57-5	0.00015	0.02000	0.00810
		Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.01004	1.30000	0.52680
		Palladium (Pd)	7440-05-3	0.00054	0.07000	0.02837
subTotal		0.77200	100.00000	40.52323		
Mould Compound	Additive	Misc. Phosphor compounds (generic)	7723-14-0	0.00107	0.10000	0.05596
		Non hazardous	Proprietary	0.03838	3.60000	2.01440
	Filler	Silica fused	60676-86-0	0.93808	88.00000	49.24098
	Pigment	Carbon black	1333-86-4	0.00213	0.20000	0.11191
	Polymer	Phenolic resin	Proprietary	0.04371	4.10000	2.29418
		Tetramethylbiphenyl diglycidyl ether	85954-11-6	0.04264	4.00000	2.23823
subTotal		1.06600	100.00000	55.95566		
Wire	Gold alloy	Gold (Au)	7440-57-5	0.01681	99.00000	0.88213
		Palladium (Pd)	7440-05-3	0.00017	1.00000	0.00891
	subTotal		0.01698	100.00000	0.89104	

Note(s):

1) This is a generic description of the substance used as the actual composition of the substances are either considered proprietary or no official CAS number is available. If a CAS number is given, it is the closest match available.

Disclaimer

All information in this document is furnished for exploratory or indicative purposes only. All information in this document is believed to be accurate and reliable. However, Nexperia does not give any representations or warranties as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. Nexperia may make changes to information published in this document at any time and without notice. Minor deviations may occur in the products from different manufacturing location. This document supersedes and replaces all information supplied prior to the publication hereof. Nothing in this document may be interpreted or construed as an offer to sell products that is open for acceptance or the grant, conveyance or implication of any license under any copyrights, patents or other industrial or intellectual property rights.